IN THE SPECIFICATION:

Please amend paragraph number **[0060]** as follows:

[0060] Turning now to FIG. 4A, conductive traces 22, which extend substantially laterally from selected ones of electrically conductive vias 21, may be fabricated so as to be carried by carrier substrate 18. Preferably, these conductive traces 22 are disposed on backside 19 of carrier substrate 18. Alternatively, conductive traces 22 may extend, at least partially, internally through carrier substrate 18. Each conductive trace 22 preferably communicates with a corresponding electrically conductive via 21 of carrier substrate 18 and, therefore, with a corresponding bond pad 16 of semiconductor device 12. Since conductive traces 22 extend substantially laterally from their corresponding electrically conductive vias 21, conductive traces 22 of carrier substrate 18 are useful for establishing electrical connections between the contacts of a substrate and bond pads 16 of a semiconductor device 12 having a different footprint than that of carrier substrate 18.

Please amend paragraph number **[0062]** as follows:

[0062] Alternatively, with reference to FIG. 4B, which illustrates the fabrication of chip-scale package 110, electrically conductive vias 121 may be fabricated by disposing the solder within apertures 120. Solder may be disposed within apertures 120 by known processes, such as by wave solder processes, by disposing a molten solder ball adjacent or in each aperture 120, or by disposing a solder brick within or adjacent to each aperture 120 and heating the solder brick to reflow the same. Preferably, as molten solder is disposed within each aperture 120, an electrically conductive via 121 is formed and substantially concurrently bonded to a corresponding bond pad 116 of semiconductor device 112.

Please amend paragraph number **[0077]** as follows:

[0077] Alternatively, with reference to FIGs. 6B and 6C, which illustrate the fabrication of chip-scale package 110, if carrier substrate 118 does not include conductive traces extending across backside 119 thereof or if only a contact region (see, *e.g.*, reference 22a of FIG. 1) of each conductive trace (see, *e.g.*, reference 22 of FIG. 1) of carrier substrate 118 is exposed to

backside 119, a substantially planar layer 126 comprising a nonconductive elastomer 125 having therein localized conductive regions 127 of a conductive elastomer, such as a z-axis elastomer or anisotropic conductive elastomer of a type known in the art, may be disposed adjacent backside 119 of carrier substrate 118. The conductive regions 127 of such a substantially planar layer 126 preferably contact each electrically conductive via 121 or contact region (*see, e.g.*, reference 22a of FIG. 1) of a conductive element (not shown in FIG. 6A or 6B) to facilitate the transmission of electrical signals through each electrically conductive via 121 of carrier substrate 118 to or from bond pads 116. Substantially planar layer 126 may be disposed on backside 119 of carrier substrate 118 by known processes, such as by securing a preformed layer of elastomer having conductive regions 127 therein to backside 119. Alternatively, a quantity of nonconductive elastomer 125 may be disposed on backside 119 and spread to a substantially uniform thickness thereacross by known techniques, such as by spin-on processes or mechanical processes (*e.g.*, the use of a doctor blade), electrically conductive vias 121 exposed through nonconductive elastomer 125, and an electrically conductive elastomer disposed adjacent electrically conductive vias 121 so as to form conductive regions 127 peripherally surrounded by nonconductive elastomer 125. The conductive components of a conductive elastomer disposed in this manner may also be aligned by known processes, such as by magnetically aligning the conductive components.